PCN Num	ber:	2023120	0.00080		PCN	l Dat	te:	December 11, 2023	
Title:	HFTF Marking	Standard	dization	for Select Devices					
		hange N	ange Management Team		Dept:		Quality Services		
Change 1	Гуре:								
Asse	mbly Site			Design			Wa	fer Bump Material	
Assembly Process				Data Sheet			Wafer Bump Process		
Assembly Materials				Part number change			Wafer Fab Site		
Mechanical Specification				Test Site			Wafer Fab Materials		
Packing/Shipping/Labeling				Test Process			Wafer Fab Process		
				PCN Details					
Descripti	on of Change								
Package	Device			Current			P	Proposed	
				(Top side)			A (14J Top side)	
	Marking			Standard			Bi	nary Code	
	Pin 1 ID			Dot				Dot	
Reason f	or Change:								
Marking S	tandardization								
Anticipat	ed impact on	Fit, Forr	n, Func	tion, Quality or Relia	ability	(po	sitiv	e / negative):	
None									
Changes	to product id	entificat	ion res	ulting from this PCN:					
None									

Product Affected:

LM3880MF-1AA/NOPB	LM3880MFE-1AA/NOPB	LM3880MFX-1AA/NOPB
LM3880MF-1AB/NOPB	LM3880MFE-1AB/NOPB	LM3880MFX-1AB/NOPB
LM3880MF-1AC/NOPB	LM3880MFE-1AC/NOPB	LM3880MFX-1AC/NOPB
LM3880MF-1AD/NOPB	LM3880MFE-1AD/NOPB	LM3880MFX-1AD/NOPB
LM3880MF-1AE/NOPB	LM3880MFE-1AE/NOPB	LM3880MFX-1AE/NOPB
LM3880MF-1AF/NOPB	LM3880MFE-1AF/NOPB	LM3880MFX-1AF/NOPB

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